

## Q. Metrology, Inspection, and Yield Enhancement **분과**

2017년 2월 15일 (수), 12:40-14:25  
Room C (사파이어, 2층)

### [WC3-Q] Metrology and Inspection (I)

좌장: 유형원(SK 하이닉스), 양준모(나노종합기술원)

<b>WC3-Q-1</b> 12:40-13:10	<b>[초청]</b> <b>New Methodology for Accurate and Robust Overlay Measurement</b> Suk-Joo Lee, Arie den Boef, Kaustuve Bhattacharyya, and Marc Noot <i>CS-NPI Apps, ASML Korea</i>
<b>WC3-Q-2</b> 13:10-13:25	<b>Improvement of Geometry-Induced Overlay Using Patterned Wafer Geometry (PWG)</b> Keunjun Kim, Yiseul Kwon, Kitaek Kang, Deokkyun Park, Jeongsu Park, Sungkoo Lee, and Hyeongsoo Kim <i>R&amp;D Division, SK Hynix Inc.</i>
<b>WC3-Q-3</b> 13:25-13:40	<b>Process Induced Overlay Error 개선을 위한 PWG IPD &amp; GEN3</b> Jun-beom Park, Hong-goo Lee, Sang-jun Han, and Chang-rok Song <i>R&amp;D Division, SK Hynix Semiconductor Inc.</i>
<b>WC3-Q-4</b> 13:40-14:10	<b>[초청]</b> <b>3D Metrology &amp; Inspection beyond the Optical Resolution Limit by Through-focus Scanning Optical Microscope</b> Jun Ho Lee <sup>1</sup> , Myungjoo Kang <sup>2</sup> , Joonghwee Cho <sup>3</sup> , Hwi Kim <sup>4</sup> , and Eun Ji Shin <sup>5</sup> <i><sup>1</sup>Department of Optical Eng., Kongju National University, <sup>2</sup>Department of Math. Sciences, Seoul National University, <sup>3</sup>Department of Elec. &amp; Info. Eng., Korea University, <sup>4</sup>Department of Embedded Systems Eng., Incheon National University</i>
<b>WC3-Q-5</b> 14:10-14:25	<b>Experimental TSOM Image based DB Construction and Measurement</b> Heechul Choi, Junhee Kang, Seungil Shin, and Joonghwee Cho <i>Department of Embedded Systems Engineering, Incheon National University</i>